IN THE CLAIMS:

CLAIMS

What is claimed is:

1. (Currently Amended) A method of forming a package device ~~(10, 100)~~, comprising;
   providing a package substrate ~~(12)~~ having a first side ~~(50, 150)~~ and a second side ~~(52, 152)~~ and having first pads ~~(16, 116)~~ on the first side and second pads ~~(16, 116)~~ on the second side;
   placing a first integrated circuit ~~(22, 122)~~ on the first side and a second integrated circuit ~~(32, 132)~~ on a second side;
   electrically connecting the first integrated circuit to the first pads and the second integrated circuit to the second pads; and
   testing the first integrated circuit and the second integrated circuit by applying test probes ~~(44, 144)~~ to the first pads and the second pads.

2. (Currently Amended) A method for forming a package device ~~(10, 100)~~, comprising:
   providing a package substrate ~~(12, 112)~~ having a first surface ~~(50, 150)~~ along a first plane and second surface ~~(52, 152)~~ along a second plane, wherein the package substrate has a cavity ~~(20, 120)~~ between the first plane and the second plane;
   placing a first integrated circuit ~~(22, 122)~~ in the cavity;
   placing a second integrated circuit ~~(32, 132)~~ adjacent to the first integrated circuit outside the cavity; and
   depositing encapsulating material ~~(28, 46, 138, 146)~~ over the first integrated circuit and the second integrated circuit.

3. (Currently Amended) The method of claim 2, wherein the step of depositing comprises:
   depositing a first portion ~~(28, 128)~~ of the encapsulating material over the first integrated circuit ~~(22, 122)~~ prior to the step of placing the second integrated circuit; and
   depositing a second portion ~~(46, 146)~~ of the encapsulating material over the second integrated circuit ~~(32, 132)~~.

4. (Currently Amended) The method of claim 2, wherein the package substrate ~~(12, 112)~~ further comprises a supporting member ~~(18, 119)~~ along the second plane ~~(52, 152)~~ of the substrate.

5. (Currently Amended) The method of claim 4, further comprising removing the supporting member ~~(18, 119)~~ prior to step of placing the second integrated circuit ~~(32, 132)~~.

6. (Currently Amended) A package device ~~(10, 100)~~, comprising:

a package substrate ~~(12, 112)~~ having a first surface ~~(50, 150)~~ defining a first plane and a second surface ~~(52, 152)~~ defining a second plane, the package substrate having a cavity ~~(20, 120)~~ between the first plane and the second plane;

a first integrated circuit ~~(22, 122)~~ in the cavity; and

a second integrated circuit ~~(32, 132)~~, coupled to the package substrate, outside the cavity.

7. (Currently Amended) A package device ~~(10, 100)~~, comprising:

a package substrate ~~(12, 112)~~ having a first side and a second side;

first pads ~~(16, 116)~~ on the first side;

second pads ~~(16, 116)~~ on the second side;

a first integrated circuit ~~(22, 122)~~ mounted to the package substrate;

wherein the first pads and the second pads are further characterized as being useful for receiving test probes ~~(44, 144)~~ for testing.

8. (Currently Amended) The package device of claim 7, further comprising a second integrated circuit ~~(32, 132)~~ mounted to the package substrate.

9. (Currently Amended) The package device of claim 8, wherein:

the first integrated circuit ~~(22, 122)~~ is electrically connected to the first pads ~~(16, 116)~~; and

the second integrated circuit ~~(32, 132)~~ is electrically connected to the second pads ~~(16, 116)~~.

10. (Currently Amended) The package device of claim 9, wherein the substrate ~~(12, 112)~~ is further characterized as having a cavity ~~(20, 120)~~ and the first integrated circuit ~~(22, 122)~~ is further characterized as being in the cavity.